



Material Content Data Sheet



Sales Product Name		BTF3050TE		Issued		1. August 2018		
MA#		MA001854608						
Package		PG-TO252-5-11		Weight*		355.08 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.424	0.40	0.40	4011	4011
leadframe	inorganic material	phosphorus	7723-14-0	0.061	0.02		173	
	non noble metal	iron	7439-89-6	0.205	0.06		576	
	non noble metal	copper	7440-50-8	204.243	57.52	57.60	575202	575951
	non noble metal	aluminium	7429-90-5	1.046	0.29	0.29	2947	2947
wire	non noble metal	aluminium	7429-90-5	1.046	0.29	0.29	2947	2947
encapsulation	organic material	carbon black	1333-86-4	1.414	0.40		3983	
	plastics	epoxy resin	-	24.748	6.97		69698	
	inorganic material	silicondioxide	60676-86-0	115.257	32.46	39.83	324595	398276
leadfinish	non noble metal	tin	7440-31-5	5.072	1.43	1.43	14285	14285
plating	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	nickel	7440-02-0	0.076	0.02	0.02	215	216
solder	non noble metal	tin	7440-31-5	0.031	0.01		86	
	noble metal	silver	7440-22-4	0.038	0.01		108	
	non noble metal	lead	7439-92-1	1.463	0.41	0.43	4120	4314
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com